



## ISO154x-Q1 Low-Power Bidirectional I<sup>2</sup>C Isolators

### 1 Features

- Qualified for Automotive Applications
- AEC-Q100 Qualified With the Following Results:
  - Device Temperature Grade 1: –40°C to +125°C Ambient Operating Temperature
  - Device HBM ESD Classification Level 3A
  - Device CDM ESD Classification Level C6
- Isolated Bidirectional, I<sup>2</sup>C Compatible, Communication
- Supports up to 1-MHz Operation
- 3-V to 5.5-V Supply Range
- Open-Drain Outputs With 3.5-mA Side 1 and 35-mA Side 2 Sink Current Capability
- ±50-kV/μs Transient Immunity (Typical)
- Safety-Related Certifications:
  - 4242-V<sub>PK</sub> Isolation per DIN V VDE V 0884-10 (VDE V 0884-10): 2006-12
  - 2500-V<sub>RMS</sub> Isolation for 1 Minute per UL 1577
  - CSA Component Acceptance Notice 5A, IEC 60950-1 and IEC 61010-1 End Equipment Standards
  - CQC Basic Insulation per GB4943.1-2011
  - UL 1577 Certification Complete; All Other Certifications Planned

### 2 Applications

- Electric and Hybrid-Electric Vehicles
- Isolated I<sup>2</sup>C Buses
- SMBus and PMBus Interfaces
- Open-Drain Networks
- Motor Control Systems
- Battery Management
- I<sup>2</sup>C Level Shifting

### 3 Description

The ISO1540-Q1 and ISO1541-Q1 devices are low-power, bidirectional isolators that are compatible with I<sup>2</sup>C interfaces. These devices have logic input and output buffers that are separated by Texas Instruments Capacitive Isolation technology using a silicon dioxide (SiO<sub>2</sub>) barrier. When used with isolated power supplies, these devices block high voltages, isolate grounds, and prevent noise currents from entering the local ground and interfering with or damaging sensitive circuitry.

This isolation technology provides for function, performance, size, and power consumption advantages when compared to optocouplers. The ISO1540-Q1 and ISO1541-Q1 devices enable a complete isolated I<sup>2</sup>C interface to be implemented within a small form factor.

The ISO1540-Q1 has two isolated bidirectional channels for clock and data lines while the ISO1541-Q1 has a bidirectional data and a unidirectional clock channel. The ISO1541-Q1 is useful in applications that have a single master while the ISO1540-Q1 is suitable for multi-master applications. For applications where clock stretching by the slave is possible, the ISO1540-Q1 device should be used.

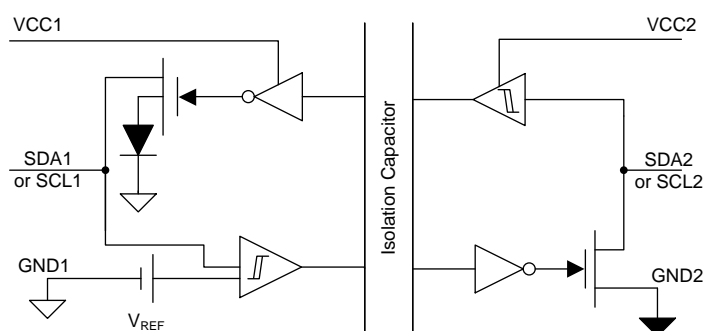
Isolated bidirectional communication is accomplished within these devices by offsetting the low-level output voltage on side 1 to a value greater than the high-level input voltage on side 1, thus preventing an internal logic latch that otherwise would occur with standard digital isolators.

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
ISO1540-Q1 ISO1541-Q1	SOIC (8)	4.90 mm x 3.91 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

#### Simplified Schematic



## Table of Contents

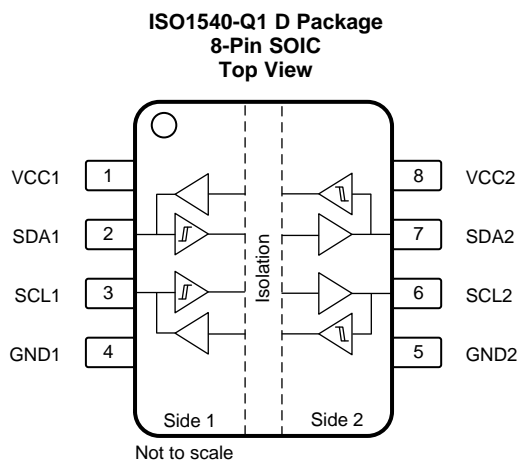
<b>1 Features</b> .....	<b>1</b>	8.1 Overview .....	17
<b>2 Applications</b> .....	<b>1</b>	8.2 Functional Block Diagrams .....	17
<b>3 Description</b> .....	<b>1</b>	8.3 Feature Description .....	18
<b>4 Revision History</b> .....	<b>2</b>	8.4 Isolator Functional Principle .....	18
<b>5 Pin Configuration and Functions</b> .....	<b>3</b>	8.5 Device Functional Modes .....	19
<b>6 Specifications</b> .....	<b>4</b>	<b>9 Application and Implementation</b> .....	<b>20</b>
6.1 Absolute Maximum Ratings .....	4	9.1 Application Information .....	20
6.2 ESD Ratings .....	4	9.2 Typical Application .....	22
6.3 Recommended Operating Conditions .....	5	<b>10 Power Supply Recommendations</b> .....	<b>24</b>
6.4 Thermal Information .....	5	<b>11 Layout</b> .....	<b>24</b>
6.5 Power Ratings .....	5	11.1 Layout Guidelines .....	24
6.6 Insulation Specifications .....	6	11.2 Layout Example .....	24
6.7 Safety-Related Certifications .....	7	<b>12 Device and Documentation Support</b> .....	<b>25</b>
6.8 Safety Limiting Values .....	7	12.1 Documentation Support .....	25
6.9 Electrical Characteristics .....	8	12.2 Related Links .....	25
6.10 Supply Current Characteristics .....	9	12.3 Receiving Notification of Documentation Updates .....	25
6.11 Timing Requirements .....	9	12.4 Community Resources .....	25
6.12 Switching Characteristics .....	10	12.5 Trademarks .....	25
6.13 Insulation Characteristics Curves .....	11	12.6 Electrostatic Discharge Caution .....	25
6.14 Typical Characteristics .....	12	12.7 Glossary .....	25
<b>7 Parameter Measurement Information</b> .....	<b>15</b>	<b>13 Mechanical, Packaging, and Orderable Information</b> .....	<b>26</b>
<b>8 Detailed Description</b> .....	<b>17</b>		

## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

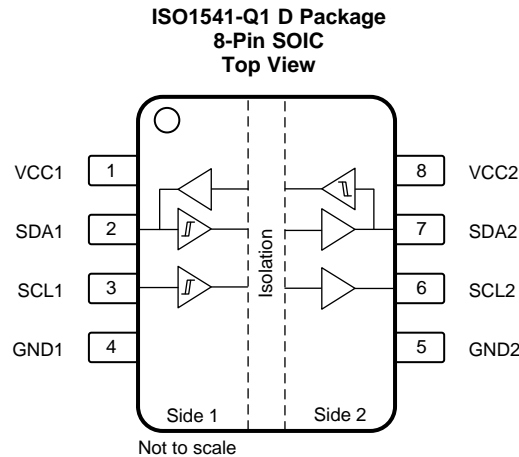
DATE	REVISION	NOTES
November 2016	*	Initial release.

## 5 Pin Configuration and Functions



**Pin Functions—ISO1540-Q1**

PIN		I/O	DESCRIPTION
NAME	NO.		
GND1	4	—	Ground, side 1
GND2	5	—	Ground, side 2
SCL1	3	I/O	Serial clock input / output, side 1
SCL2	6	I/O	Serial clock input / output, side 2
SDA1	2	I/O	Serial data input / output, side 1
SDA2	7	I/O	Serial data input / output, side 2
VCC1	1	—	Supply voltage, side 1
VCC2	8	—	Supply voltage, side 2



### Pin Functions—ISO1541-Q1

PIN		I/O	DESCRIPTION
NAME	NO.		
GND1	4	—	Ground, side 1
GND2	5	—	Ground, side 2
SCL1	3	I	Serial clock input, side 1
SCL2	6	O	Serial clock output, side 2
SDA1	2	I/O	Serial data input / output, side 1
SDA2	7	I/O	Serial data input / output, side 2
VCC1	1	—	Supply voltage, side 1
VCC2	8	—	Supply voltage, side 2

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)(2)</sup>

		MIN	MAX	UNIT
Voltage	VCC1, VCC2	−0.5	6	V
	SDA1, SCL1	−0.5	VCC1 + 0.5 <sup>(3)</sup>	
	SDA2, SCL2	−0.5	VCC2 + 0.5 <sup>(3)</sup>	
I <sub>O</sub> Output current	SDA1, SCL1	−20	20	mA
	SDA2, SCL2	−100	100	
T <sub>J(MAX)</sub> Maximum junction temperature			150	°C
T <sub>stg</sub> Storage temperature		−65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values here within are with respect to the local ground pin (GND1 or GND2) and are peak voltage values.
- (3) Maximum voltage must not exceed 6 V.

### 6.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub> Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 <sup>(1)</sup>	All pins except bus pins	±4000	V
		Bus pins	±8000	
	Charged-device model (CDM), per AEC Q100-011		±1500	

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 6.3 Recommended Operating Conditions

		MIN	MAX	UNIT
VCC1, VCC2	Supply voltage	3	5.5	V
V <sub>SDA1</sub> , V <sub>SCL1</sub>	Input and output signal voltages, side 1	0	VCC1	V
V <sub>SDA2</sub> , V <sub>SCL2</sub>	Input and output signal voltages, side 2	0	VCC2	V
V <sub>IL1</sub>	Low-level input voltage, side 1	0	0.5	V
V <sub>IH1</sub>	High-level input voltage, side 1	0.7 × VCC1	VCC1	V
V <sub>IL2</sub>	Low-level input voltage, side 2	0	0.3 × VCC2	V
V <sub>IH2</sub>	High-level input voltage, side 2	0.7 × VCC2	VCC2	V
I <sub>OL1</sub>	Output current, side 1	0.5	3.5	mA
I <sub>OL2</sub>	Output current, side 2	0.5	35	mA
C1	Capacitive load, side 1		40	pF
C2	Capacitive load, side 2		400	pF
f <sub>MAX</sub>	Operating frequency <sup>(1)</sup>		1	MHz
T <sub>A</sub>	Ambient temperature	−40	125	°C
T <sub>J</sub>	Junction temperature	−40	136	°C
T <sub>SD</sub>	Thermal shutdown	139	171	°C

(1) This represents the maximum frequency with the maximum bus load (C) and the maximum current sink (I<sub>O</sub>). If the system has less bus capacitance, then higher frequencies can be achieved.

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		ISO154x-Q1	UNIT
		D (SOIC)	
		8 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	114.6	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	69.6	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	55.3	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	27.2	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	54.7	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report (SPRA953).

### 6.5 Power Ratings

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
P <sub>D</sub>	Maximum power dissipation (both sides)			85	mW
P <sub>D1</sub>	Maximum power dissipation (side-1)			34	mW
P <sub>D2</sub>	Maximum power dissipation (side-2)			51	mW

VCC1 = VCC2 = 5.5 V, T<sub>J</sub> = 150 °C, C1 = 40 pF, C2 = 400 pF;  
Input a 1-MHz 50% duty cycle clock signal

## 6.6 Insulation Specifications

PARAMETER		TEST CONDITIONS	VALUE	UNIT
GENERAL				
CLR	External clearance <sup>(1)</sup>	Shortest terminal-to-terminal distance through air	>4	mm
CPG	External creepage <sup>(1)</sup>	Shortest terminal-to-terminal distance across the package surface	>4	mm
DTI	Distance through the insulation	Minimum internal gap (internal clearance)	0.014	mm
CTI	Comparative tracking index	DIN EN 60112 (VDE 0303-11); IEC 60112	>400	V
	Material group		II	
	Overvoltage category	Rated mains voltage ≤ 150 V <sub>RMS</sub>	I–IV	
		Rated mains voltage ≤ 300 V <sub>RMS</sub>	I–III	
DIN V VDE V 0884-10 (VDE V 0884-10):2006-12 <sup>(2)</sup>				
V <sub>IORM</sub>	Maximum repetitive peak isolation voltage	AC voltage (bipolar)	566	V <sub>PK</sub>
V <sub>IOTM</sub>	Maximum transient isolation voltage	V <sub>TEST</sub> = V <sub>IOTM</sub> t = 60 s (qualification) t = 1 s (100% production)	4242	V <sub>PK</sub>
q <sub>pd</sub>	Apparent charge <sup>(3)</sup>	Method a: After I/O safety test subgroup 2/3, V <sub>ini</sub> = V <sub>IOTM</sub> , t <sub>ini</sub> = 60 s; V <sub>pd(m)</sub> = 1.2 × V <sub>IORM</sub> = 680 V <sub>PK</sub> , t <sub>m</sub> = 10 s	<5	pC
		Method a: After environmental tests subgroup 1, V <sub>ini</sub> = V <sub>IOTM</sub> , t <sub>ini</sub> = 60 s; V <sub>pd(m)</sub> = 1.6 × V <sub>IORM</sub> = 906 V <sub>PK</sub> , t <sub>m</sub> = 10 s	<5	
		Method b1: At routine test (100% production) and preconditioning (type test) V <sub>ini</sub> = V <sub>IOTM</sub> , t <sub>ini</sub> = 1 s; V <sub>pd(m)</sub> = 1.875 × V <sub>IORM</sub> = 1062 V <sub>PK</sub> , t <sub>m</sub> = 1 s	<5	
C <sub>IO</sub>	Barrier capacitance, input to output <sup>(4)</sup>	V <sub>IO</sub> = 0.4 sin (2πft), f = 1 MHz	~1	pF
R <sub>IO</sub>	Isolation resistance, input to output <sup>(4)</sup>	V <sub>IO</sub> = 500 V, T <sub>A</sub> = 25°C	>10 <sup>12</sup>	Ω
		V <sub>IO</sub> = 500 V, 100°C ≤ T <sub>A</sub> ≤ 125°C	>10 <sup>11</sup>	
		V <sub>IO</sub> = 500 V at T <sub>S</sub> = 150°C	>10 <sup>9</sup>	
	Pollution degree		2	
	Climatic category		40/125/21	
UL 1577				
V <sub>ISO</sub>	Withstand isolation voltage	V <sub>TEST</sub> = V <sub>ISO</sub> = 2500 V <sub>RMS</sub> , t = 60 s (qualification); V <sub>TEST</sub> = 1.2 × V <sub>ISO</sub> = 3000 V <sub>RMS</sub> , t = 1 s (100% production)	2500	V <sub>RMS</sub>

- (1) Creepage and clearance requirements should be applied according to the specific equipment isolation standards of an application. Care should be taken to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed-circuit board do not reduce this distance. Creepage and clearance on a printed-circuit board become equal in certain cases. Techniques such as inserting grooves and/or ribs on a printed circuit board are used to help increase these specifications.
- (2) This coupler is suitable for *basic electrical insulation* only within the maximum operating ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.
- (3) Apparent charge is electrical discharge caused by a partial discharge (pd).
- (4) All pins on each side of the barrier tied together creating a two-terminal device

## 6.7 Safety-Related Certifications

VDE	CSA	UL	CQC
Plan to certify according to DIN V VDE V 0884-10 (VDE V 0884-10):2006-12 and DIN EN 61010-1 (VDE 0411-1):2011-07	Plan to certify under CSA Component Acceptance Notice 5A, CSA/IEC 60950-1, and CSA/IEC 61010-1	Recognized under UL 1577 Component Recognition Program	Plan to certify according to GB4943.1-2011
Basic Insulation Maximum Transient Overvoltage, 4242 V <sub>PK</sub> ; Maximum Repetitive Peak Voltage, 566 V <sub>PK</sub>	2.8-kV <sub>RMS</sub> Insulation Rating; 400 V <sub>RMS</sub> Basic Insulation working voltage per CSA 60950-1-07+A1+A2 and IEC 60950-1 2nd Ed.+A1+A2; 300 V <sub>RMS</sub> Basic, 150 V <sub>RMS</sub> Reinforced Insulation working voltage per CSA 61010-1-12 and IEC 61010-1 3rd Ed.,	Single protection, 2500 V <sub>RMS</sub>	Basic Insulation, Altitude ≤ 5000 m, Tropical Climate, 250 V <sub>RMS</sub> maximum working voltage
Certification planned	Certification planned	File number: E181974	Certification planned

## 6.8 Safety Limiting Values

Safety limiting intends to minimize potential damage to the isolation barrier upon failure of input or output circuitry. A failure of the I/O can allow low resistance to ground or the supply and, without current limiting, dissipate sufficient power to overheat the die and damage the isolation barrier, potentially leading to secondary system failures.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I <sub>S</sub> Safety input, output, or supply current	R <sub>θJA</sub> = 114.6°C/W, V <sub>I</sub> = 5.5 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">Figure 1</a>			198	mA
	R <sub>θJA</sub> = 114.6°C/W, V <sub>I</sub> = 3.6 V, T <sub>J</sub> = 150°C, T <sub>A</sub> = 25°C, see <a href="#">Figure 1</a>			303	
T <sub>S</sub> Safety temperature				150	°C

The safety-limiting constraint is the maximum junction temperature specified in the data sheet. The power dissipation and junction-to-air thermal impedance of the device installed in the application hardware determines the junction temperature. The assumed junction-to-air thermal resistance in the [Thermal Information](#) table is that of a device installed on a high-K test board for leaded surface-mount packages. The power is the recommended maximum input voltage times the current. The junction temperature is then the ambient temperature plus the power times the junction-to-air thermal resistance.

## 6.9 Electrical Characteristics

over recommended operating conditions, unless otherwise noted

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>SIDE 1 (ONLY)</b>						
V <sub>ILT1</sub>	Voltage input threshold low, SDA1 and SCL1		500	550	660	mV
V <sub>IHT1</sub>	Voltage input threshold high, SDA1 and SCL1		540	610	700	mV
V <sub>HYST1</sub>	Voltage input hysteresis	V <sub>IHT1</sub> – V <sub>ILT1</sub>	40	60		mV
V <sub>OL1</sub>	Low-level output voltage, SDA1 and SCL1 <sup>(1)</sup>	0.5 mA ≤ (I <sub>SDA1</sub> and I <sub>SCL1</sub> ) ≤ 3.5 mA	650		800	mV
ΔV <sub>OIT1</sub>	Low-level output voltage to high-level input voltage threshold difference, SDA1 and SCL1 <sup>(1)(2)</sup>	0.5 mA ≤ (I <sub>SDA1</sub> and I <sub>SCL1</sub> ) ≤ 3.5 mA	50			mV
<b>SIDE 2 (ONLY)</b>						
V <sub>ILT2</sub>	Voltage input threshold low, SDA2 and SCL2		0.3 × VCC2	0.4 × VCC2		V
V <sub>IHT2</sub>	Voltage input threshold high, SDA2 and SCL2		0.4 × VCC2	0.5 × VCC2		V
V <sub>HYST2</sub>	Voltage input hysteresis	V <sub>IHT2</sub> – V <sub>ILT2</sub>	0.05 × VCC2			V
V <sub>OL2</sub>	Low-level output voltage, SDA2 and SCL2	0.5 mA ≤ (I <sub>SDA2</sub> and I <sub>SCL2</sub> ) ≤ 35 mA			0.4	V
<b>BOTH SIDES</b>						
I <sub>I</sub>	Input leakage currents, SDA1, SCL1, SDA2, and SCL2	V <sub>SDA1</sub> , V <sub>SCL1</sub> = VCC1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = VCC2		0.01	10	μA
C <sub>I</sub>	Input capacitance to local ground, SDA1, SCL1, SDA2, and SCL2	V <sub>I</sub> = 0.4 × sin(2E6πt) + 2.5 V		7		pF
CMTI	Common-mode transient immunity	See <a href="#">Figure 21</a>	25	50		kV/μs
V <sub>CCUV</sub>	VCC undervoltage lockout threshold <sup>(3)</sup>		2.1	2.5	2.8	V

(1) This parameter does not apply to the ISO1541-Q1 SCL1 line as it is unidirectional.

(2) ΔV<sub>OIT1</sub> = V<sub>OL1</sub> – V<sub>IHT1</sub>. This represents the minimum difference between a Low-Level Output Voltage and a High-Level Input Voltage Threshold to prevent a permanent latch condition that would otherwise exist with bidirectional communication.

(3) Any VCC voltages, on either side, less than the minimum will ensure device lockout. Both VCC voltages greater than the maximum will prevent device lockout.



## 6.10 Supply Current Characteristics

over recommended operating conditions, unless otherwise noted. For more information, see [Figure 19](#).

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
3 V ≤ VCC1, VCC2 ≤ 3.6 V							
I <sub>CC1</sub>	Supply current, side 1	ISO1540-Q1	V <sub>SDA1</sub> , V <sub>SCL1</sub> = GND1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = GND2; R1, R2 = Open; C1, C2 = Open		2.4	3.6	mA
			V <sub>SDA1</sub> , V <sub>SCL1</sub> = VCC1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = VCC2; R1, R2 = Open; C1, C2 = Open		2.5	3.8	
	ISO1541-Q1	V <sub>SDA1</sub> , V <sub>SCL1</sub> = GND1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = GND2; R1, R2 = Open; C1, C2 = Open		2.1	3.3		
		V <sub>SDA1</sub> , V <sub>SCL1</sub> = VCC1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = VCC2; R1, R2 = Open; C1, C2 = Open		2.3	3.6		
I <sub>CC2</sub>	Supply current, side 2	ISO1540-Q1 and ISO1541-Q1	V <sub>SDA1</sub> , V <sub>SCL1</sub> = GND1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = GND2; R1, R2 = Open; C1, C2 = Open		1.7	2.7	mA
			V <sub>SDA1</sub> , V <sub>SCL1</sub> = VCC1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = VCC2; R1, R2 = Open; C1, C2 = Open		1.9	3.1	
4.5 V ≤ VCC1, VCC2 ≤ 5.5 V							
I <sub>CC1</sub>	Supply current, side 1	ISO1540-Q1	V <sub>SDA1</sub> , V <sub>SCL1</sub> = GND1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = GND2; R1,R2 = Open; C1,C2 = Open		3.1	4.7	mA
			V <sub>SDA1</sub> , V <sub>SCL1</sub> = VCC1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = VCC2; R1, R2 = Open; C1, C2 = Open		3.1	4.7	
	ISO1541-Q1	V <sub>SDA1</sub> , V <sub>SCL1</sub> = GND1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = GND2; R1, R2 = Open; C1, C2 = Open		2.8	4.4		
		V <sub>SDA1</sub> , V <sub>SCL1</sub> = VCC1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = VCC2; R1, R2 = Open; C1, C2 = Open		2.9	4.5		
I <sub>CC2</sub>	Supply current, side 2	ISO1540-Q1 and ISO1541-Q1	V <sub>SDA1</sub> , V <sub>SCL1</sub> = GND1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = GND2; R1, R2 = Open; C1, C2 = Open		2.3	3.7	mA
			V <sub>SDA1</sub> , V <sub>SCL1</sub> = VCC1; V <sub>SDA2</sub> , V <sub>SCL2</sub> = VCC2; R1, R2 = Open; C1, C2 = Open		2.5	4	

## 6.11 Timing Requirements

			MIN	NOM	MAX	UNIT
t <sub>SP</sub>	Input noise filter		5	12		ns
t <sub>UVLO</sub>	Time to recover from UVLO	2.7 V to 0.9 V; See <a href="#">Figure 22</a>	30	50	110	μs

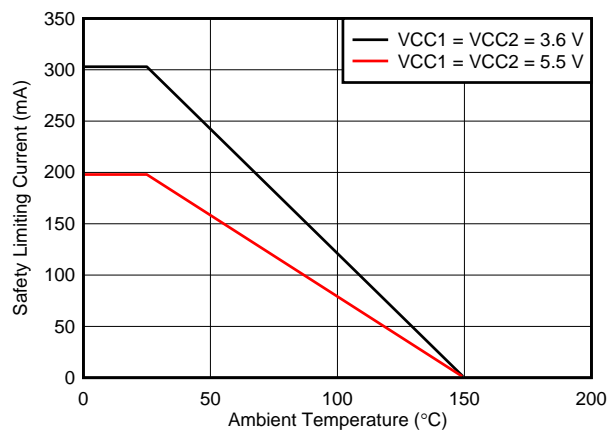
## 6.12 Switching Characteristics

over recommended operating conditions, unless otherwise noted

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
3 V ≤ VCC1, VCC2 ≤ 3.6 V							
t <sub>f1</sub>	Output Signal Fall Time (SDA1, SCL1)	See <a href="#">Figure 19</a> R1 = 953 Ω, C1 = 40 pF	0.7 × VCC1 to 0.3 × VCC1	8	17	29	ns
			0.9 × VCC1 to 900 mV	16	29	48	
t <sub>f2</sub>	Output Signal Fall Time (SDA2, SCL2)	See <a href="#">Figure 19</a> R2 = 95.3 Ω, C2 = 400 pF	0.7 × VCC2 to 0.3 × VCC2	14	23	47	ns
			0.9 × VCC2 to 400 mV	35	50	100	
t <sub>pLH1-2</sub>	Low-to-High Propagation Delay, Side 1 to Side 2	See <a href="#">Figure 19</a> R1 = 953 Ω, R2 = 95.3 Ω, C1, C2 = 10 pF	0.55 V to 0.7 × VCC2		33	65	ns
t <sub>pHL1-2</sub>	High-to-Low Propagation Delay, Side 1 to Side 2		0.7 V to 0.4 V		90	181	ns
PWD <sub>1-2</sub>	Pulse Width Distortion  t <sub>pHL1-2</sub> – t <sub>pLH1-2</sub>				55	123	ns
t <sub>pLH2-1</sub> <sup>(1)</sup>	Low-to-High Propagation Delay, Side 2 to Side 1		0.4 × VCC2 to 0.7 × VCC1		47	68	ns
t <sub>pHL2-1</sub> <sup>(1)</sup>	High-to-Low Propagation Delay, Side 2 to Side 1		0.4 × VCC2 to 0.9 V		67	109	ns
PWD <sub>2-1</sub> <sup>(1)</sup>	Pulse Width Distortion  t <sub>pHL2-1</sub> – t <sub>pLH2-1</sub>				20	49	ns
t <sub>LOOP1</sub> <sup>(1)</sup>	Round-trip propagation delay on Side 1	See <a href="#">Figure 20</a> ; R1 = 953 Ω, C1 = 40 pF R2 = 95.3 Ω, C2 = 400 pF	0.4 V to 0.3 × VCC1		100	165	ns
4.5 V ≤ VCC1, VCC2 ≤ 5.5 V							
t <sub>f1</sub>	Output Signal Fall Time (SDA1, SCL1)	See <a href="#">Figure 19</a> R1 = 1430 Ω, C1 = 40 pF	0.7 × VCC1 to 0.3 × VCC1	6	11	20	ns
			0.9 × VCC1 to 900 mV	13	21	39	
t <sub>f2</sub>	Output Signal Fall Time (SDA2, SCL2)	See <a href="#">Figure 19</a> R2 = 143 Ω, C2 = 400 pF	0.7 × VCC2 to 0.3 × VCC2	10	18	35	ns
			0.9 × VCC2 to 400 mV	28	41	76	
t <sub>pLH1-2</sub>	Low-to-High Propagation Delay, Side 1 to Side 2	See <a href="#">Figure 19</a> R1 = 1430 Ω, R2 = 143 Ω, C1,2 = 10 pF	0.55 V to 0.7 × VCC2		31	62	ns
t <sub>pHL1-2</sub>	High-to-Low Propagation Delay, Side 1 to Side 2		0.7 V to 0.4 V		70	139	ns
PWD <sub>1-2</sub>	Pulse Width Distortion  t <sub>pHL1-2</sub> – t <sub>pLH1-2</sub>				38	80	ns
t <sub>pLH2-1</sub> <sup>(1)</sup>	Low-to-high propagation delay, side 2 to side 1		0.4 × VCC2 to 0.7 × VCC1		55	80	ns
t <sub>pHL2-1</sub> <sup>(1)</sup>	High-to-low propagation delay, Side 2 to side 1		0.4 × VCC2 to 0.9 V		47	85	ns
PWD <sub>2-1</sub> <sup>(1)</sup>	Pulse Width Distortion  t <sub>pHL2-1</sub> – t <sub>pLH2-1</sub>				8	21	ns
t <sub>LOOP1</sub> <sup>(1)</sup>	Round-trip propagation delay on side 1	See <a href="#">Figure 20</a> ; R1 = 1430 Ω, C1 = 40 pF R2 = 143 Ω, C2 = 400 pF	0.4 V to 0.3 × VCC1		110	180	ns

(1) This parameter does not apply to the ISO1541-Q1 SCL1 line as it is unidirectional.

## 6.13 Insulation Characteristics Curves



**Figure 1. Thermal Derating Curve for Limiting Current per VDE**

## 6.14 Typical Characteristics

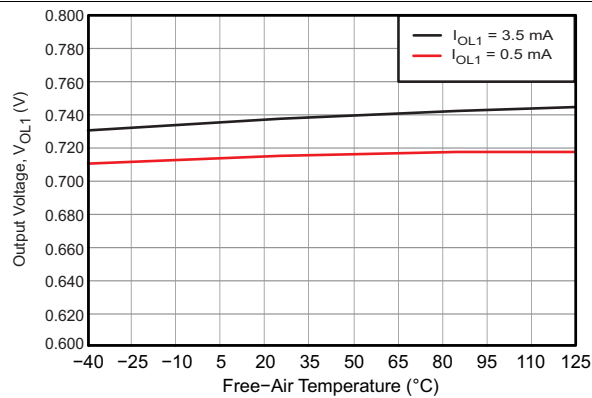


Figure 2. Side 1: Output Low Voltage vs Free-Air Temperature

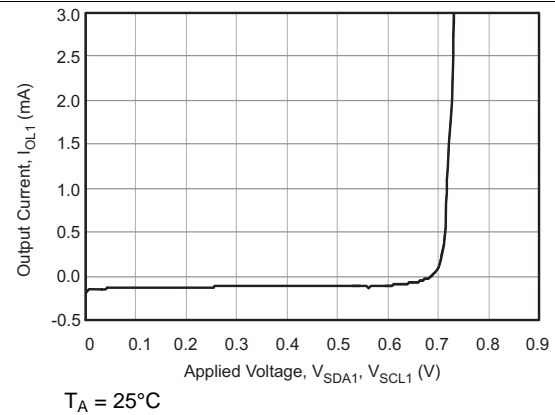


Figure 3. Side 1: Output Low Current vs  $S_{DA1}$  or  $S_{CL1}$  Applied Voltage

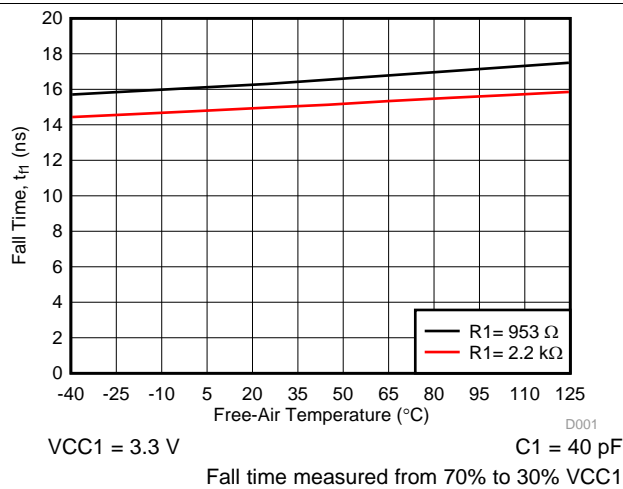


Figure 4. Side 1: Output Fall Time vs Free-Air Temperature

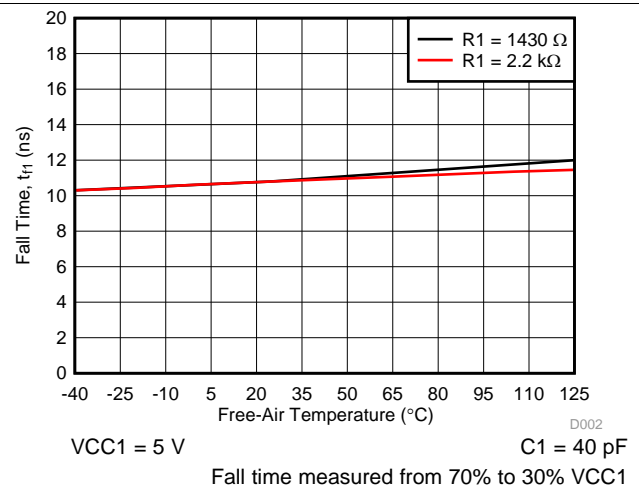


Figure 5. Side 1: Output Fall Time vs Free-air Temperature

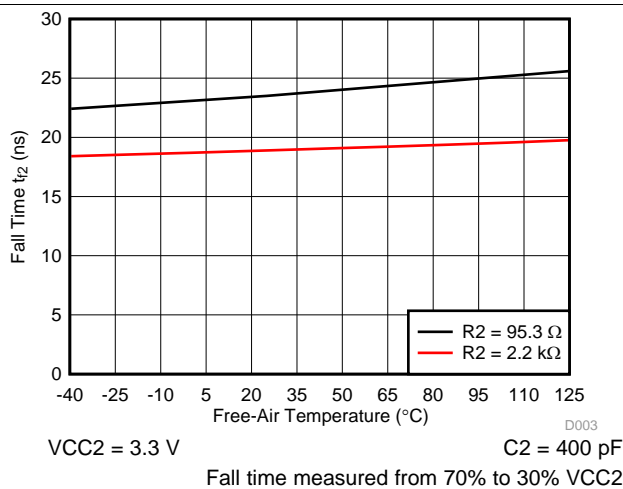


Figure 6. Side 2: Output Fall Time vs Free-Air Temperature

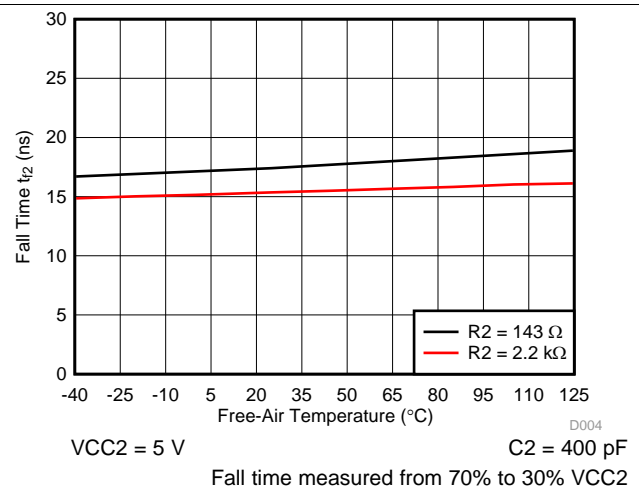


Figure 7. Side 2: Output Fall Time vs Free-Air Temperature

## Typical Characteristics (continued)

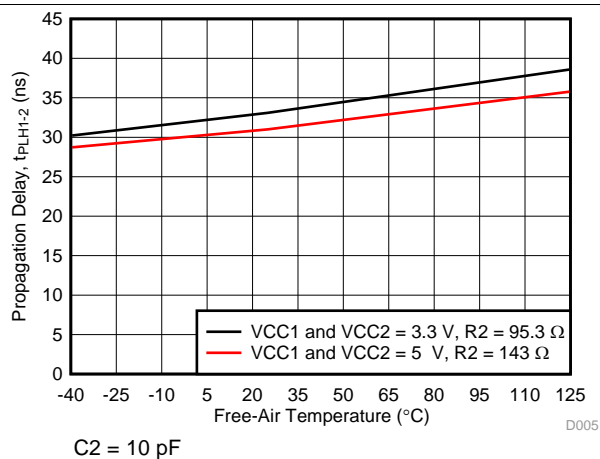


Figure 8.  $t_{PLH1-2}$  Propagation Delay vs Free-Air Temperature

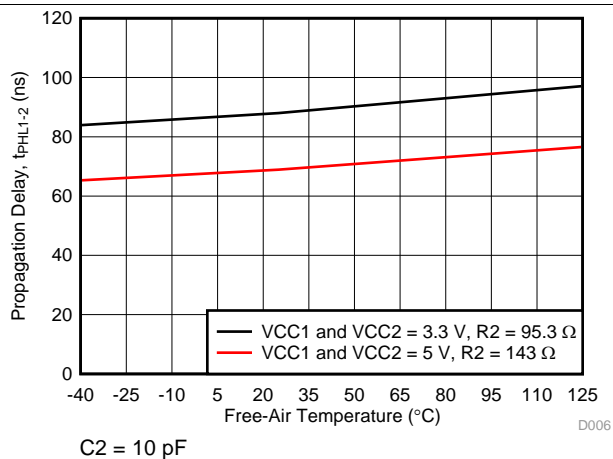


Figure 9.  $t_{PHL1-2}$  Propagation Delay vs Free-Air Temperature

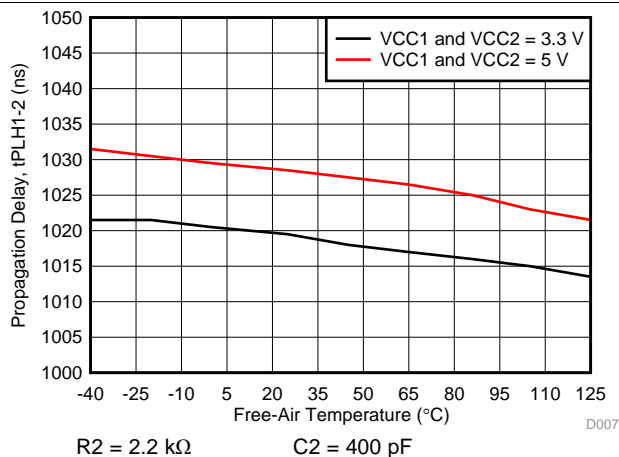


Figure 10.  $t_{PLH1-2}$  Propagation Delay vs Free-Air Temperature

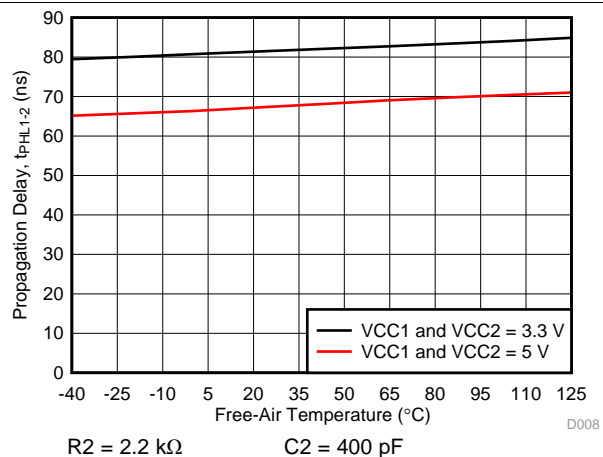


Figure 11.  $t_{PHL1-2}$  Propagation Delay vs Free-Air Temperature

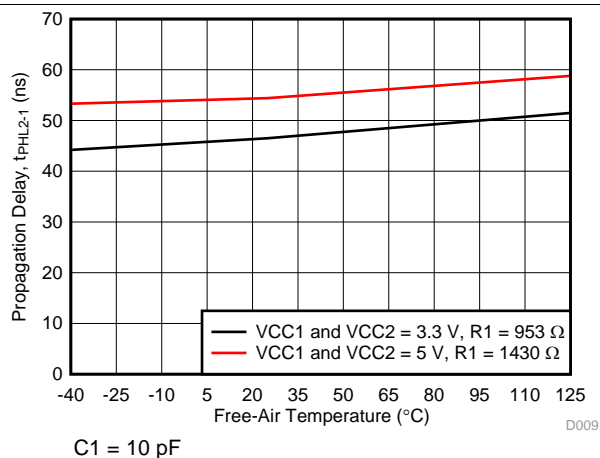


Figure 12.  $t_{PLH2-1}$  Propagation Delay vs Free-Air Temperature

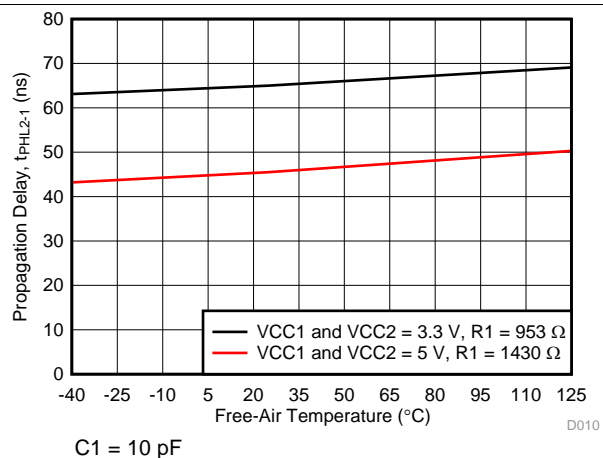
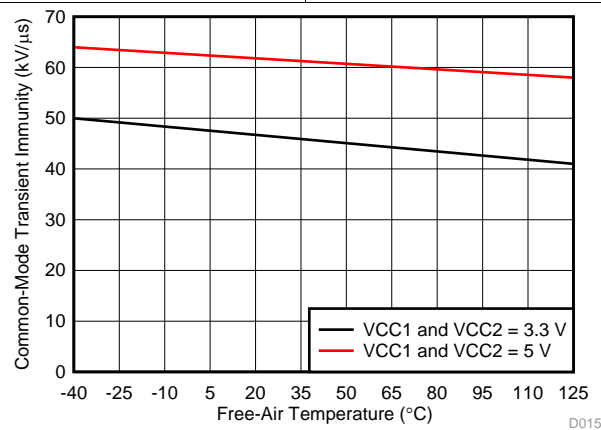
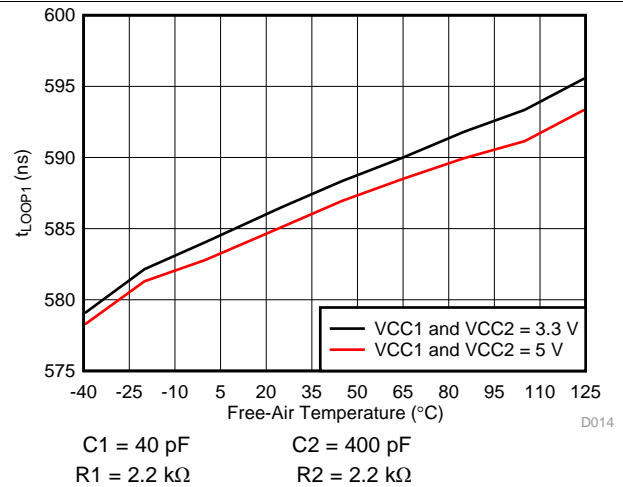
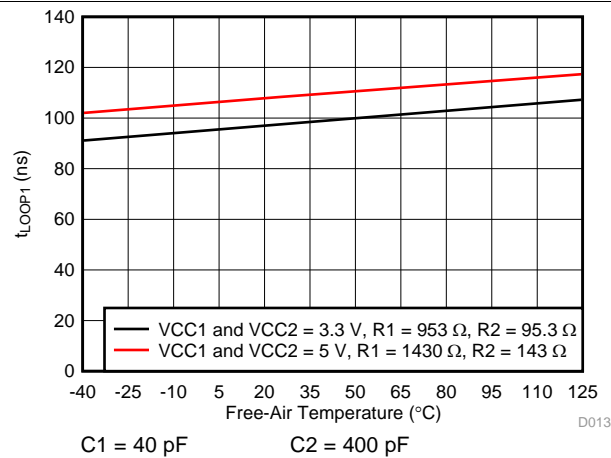
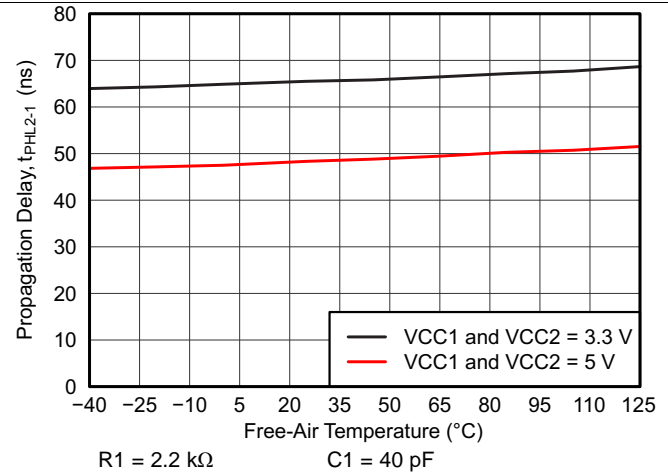
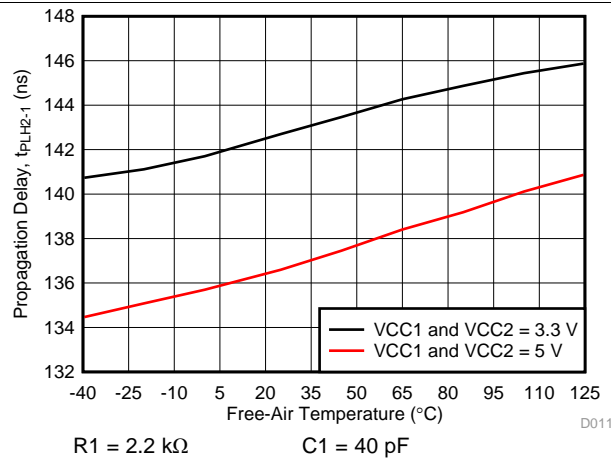
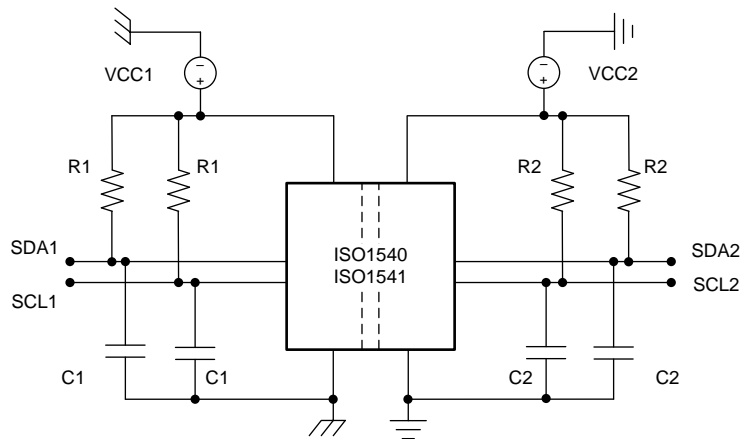


Figure 13.  $t_{PHL2-1}$  Propagation Delay vs Free-Air Temperature

## Typical Characteristics (continued)

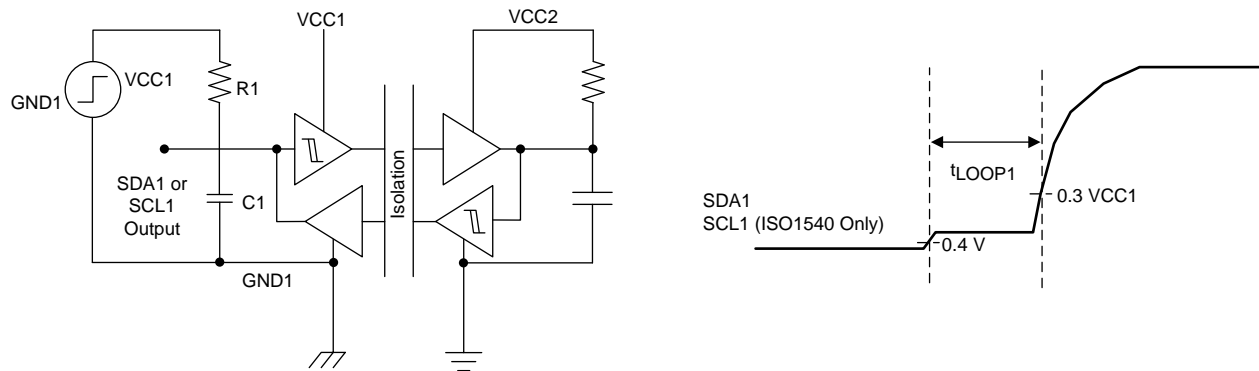


## 7 Parameter Measurement Information



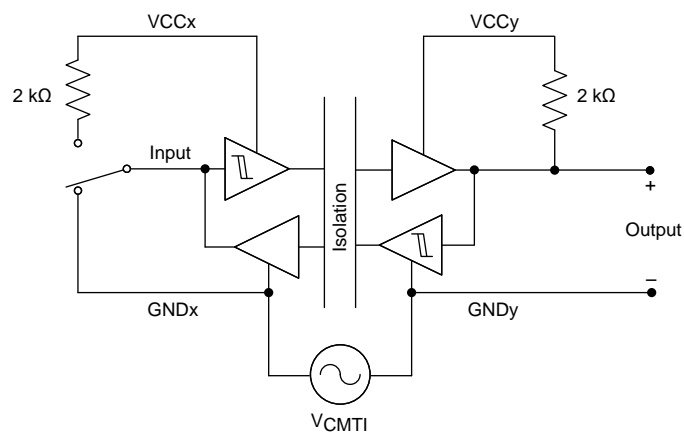
Copyright © 2016, Texas Instruments Incorporated

**Figure 19. Test Diagram**



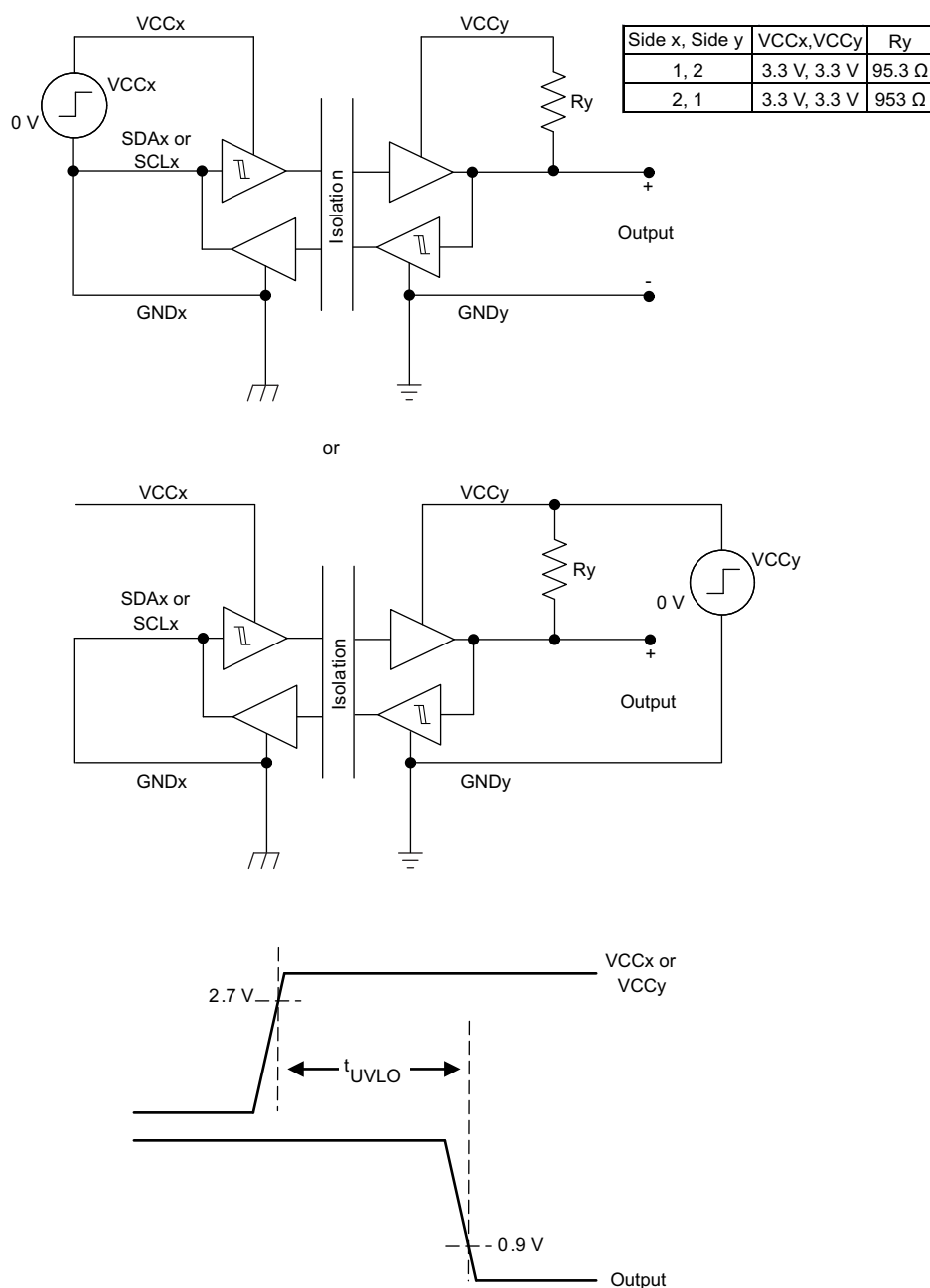
Copyright © 2016, Texas Instruments Incorporated

**Figure 20.  $t_{Loop1}$  Setup and Timing Diagram**



**Figure 21. Common-Mode Transient Immunity Test Circuit**

## Parameter Measurement Information (continued)





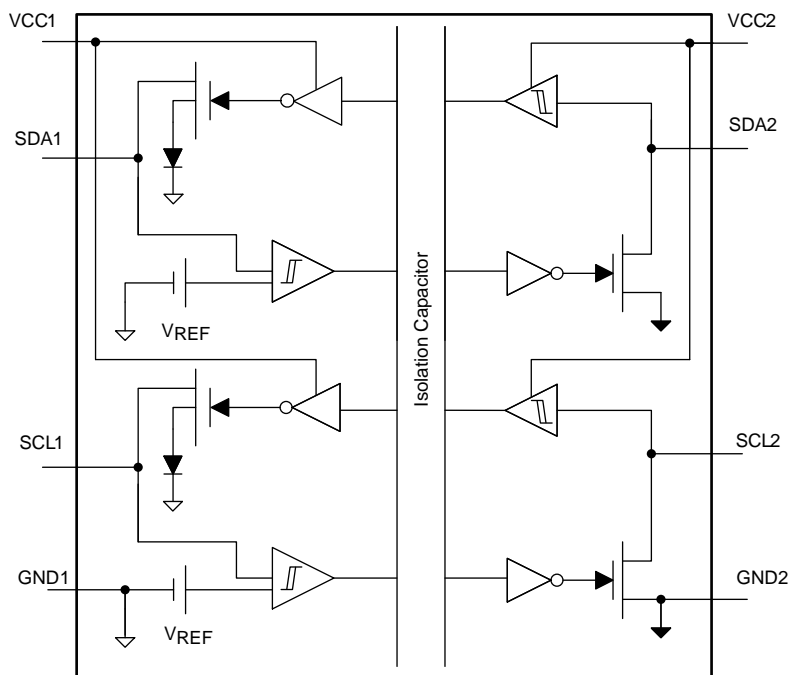
## 8 Detailed Description

### 8.1 Overview

The I<sup>2</sup>C bus is used in a wide range of applications because it is simple to use. The bus consists of a two-wire communication bus that supports bidirectional data transfer between a master device and several slave devices. The master, or processor, controls the bus, specifically the serial clock (SCL) line. Data is transferred between the master and slave through a serial data (SDA) line. This data can be transferred in four speeds: standard mode (0 to 100 kbps), fast mode (0 to 400 kbps), fast-mode plus (0 to 1 Mbps), and high-speed mode (0 to 3.4 Mbps). The most common speeds are the standard and fast modes.

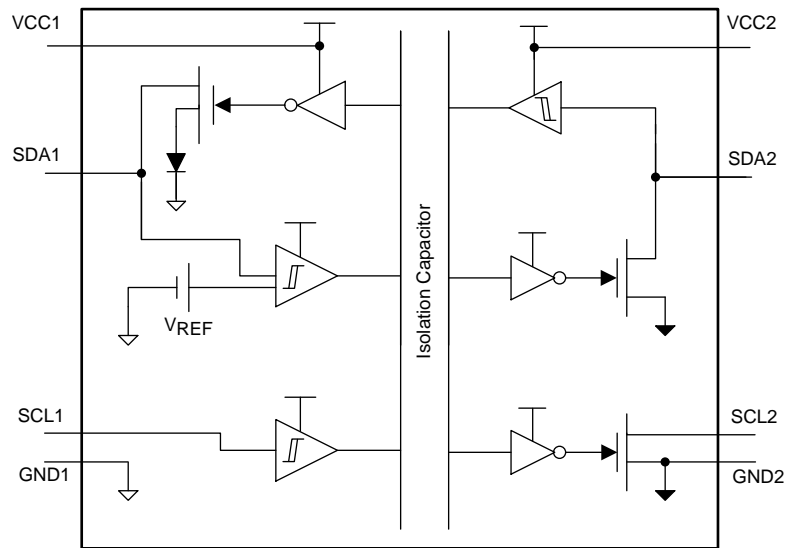
The I<sup>2</sup>C bus operates in bidirectional, half-duplex mode, while standard digital isolators are unidirectional devices. To make efficient use of one technology supporting the other, external circuitry is required that separates the bidirectional bus into two unidirectional signal paths without introducing significant propagation delay. These devices have their logic input and output buffers separated by TI's capacitive isolation technology using a silicon dioxide (SiO<sub>2</sub>) barrier. When used in conjunction with isolated power supplies, these devices block high voltages, isolate grounds, and prevent noise currents from entering the local ground and interfering with or damaging sensitive circuitry.

### 8.2 Functional Block Diagrams



**Figure 23. ISO1540-Q1 Block Diagram**

## Functional Block Diagrams (continued)



**Figure 24. ISO1541-Q1 Block Diagram**

## 8.3 Feature Description

The device enables a complete isolated I<sup>2</sup>C interface to be implemented within a small form factor having the features listed in [Table 1](#).

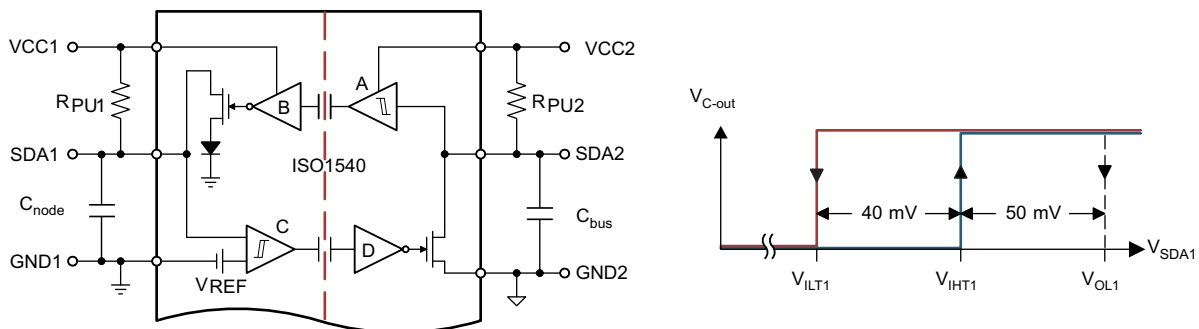
**Table 1. Features List**

PART NUMBER	CHANNEL DIRECTION	RATED ISOLATION <sup>(1)</sup>	MAXIMUM FREQUENCY
ISO1540-Q1	Bidirectional (SCL) Bidirectional (SDA)	2500 V <sub>RMS</sub> 4242 V <sub>PK</sub>	1 MHz
ISO1541-Q1	Unidirectional (SCL) Bidirectional (SDA)		

(1) See [Safety-Related Certifications](#) for detailed Isolation specifications.

## 8.4 Isolator Functional Principle

To isolate a bidirectional signal path (SDA or SCL), the ISO1540-Q1 internally splits a bidirectional line into two unidirectional signal lines, each of which is isolated through a single-channel digital isolator. Each channel output is made open-drain to comply with the open-drain technology of I<sup>2</sup>C. Side 1 of the ISO1540-Q1 connects to a low-capacitance I<sup>2</sup>C node, while side 2 is designed for connecting to a fully loaded I<sup>2</sup>C bus with up to 400 pF of capacitance.



Copyright © 2016, Texas Instruments Incorporated

**Figure 25. SDA Channel Design and Voltage Levels at SDA1**

## Isolator Functional Principle (continued)

At first sight, the arrangement of the internal buffers suggests a closed signal loop that is prone to latch-up. However, this loop is broken by implementing an output buffer (B) whose output low-level is raised by a diode drop to approximately 0.75 V, and the input buffer (C) that consists of a comparator with defined hysteresis. The comparator's upper and lower input thresholds then distinguish between the proper low-potential of 0.4 V (maximum) driven directly by SDA1 and the buffered output low-level of B.

Figure 26 demonstrate the switching behavior of the I<sup>2</sup>C isolator, ISO1540-Q1, between a master node at SDA1 and a heavy loaded bus at SDA2.

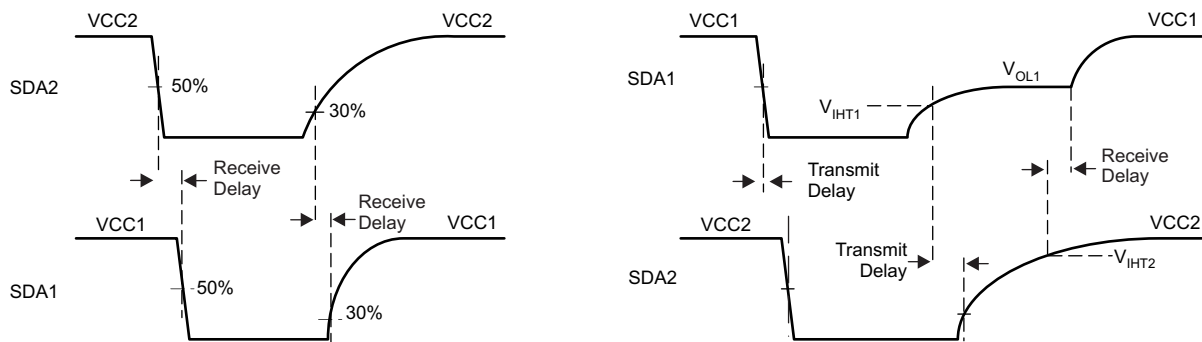


Figure 26. SDA Channel Timing in Receive and Transmit Directions

### 8.4.1 Receive Direction (Left Diagram of Figure 26)

When the I<sup>2</sup>C bus drives SDA2 low, SDA1 follows after a certain delay in the receive path. The output low is the buffered output of  $V_{OL1} = 0.75$  V, which is sufficiently low to be detected by Schmitt-trigger inputs with a minimum input-low voltage of  $V_{IL} = 0.9$  V at 3 V supply levels.

When SDA2 is released, its voltage potential increases towards VCC2 following the time-constant formed by  $R_{PU2}$  and  $C_{bus}$ . After the receive delay, SDA1 is released and also rises towards VCC1, following the time-constant  $R_{PU1} \times C_{node}$ . Because of the significant lower time-constant, SDA1 may reach VCC1 before SDA2 reaches VCC2 potential.

### 8.4.2 Transmit Direction (Right Diagram of Figure 26)

When a master drives SDA1 low, SDA2 follows after a certain delay in the transmit direction. When SDA2 turns low it also causes the output of buffer B to turn low but at a higher 0.75 V level. This level cannot be observed immediately as it is overwritten by the lower low-level of the master.

However, when the master releases SDA1, the voltage potential increases and first must pass the upper input threshold of the comparator,  $V_{IHT1}$ , to release SDA2. SDA1 then increases further until it reaches the buffered output level of  $V_{OL1} = 0.75$  V, maintained by the receive path. When comparator C turns high, SDA2 is released after the delay in transmit direction. It takes another receive delay until B's output turns high and fully releases SDA1 to move toward VCC1 potential.

## 8.5 Device Functional Modes

Table 2 lists the ISO154x-Q1 functional modes.

Table 2. Function Table<sup>(1)</sup>

POWER STATE	INPUT	OUTPUT
VCC1 or VCC2 < 2.1 V	X	Z
VCC1 and VCC2 > 2.8 V	L	L
VCC1 and VCC2 > 2.8 V	H	Z
VCC1 and VCC2 > 2.8 V	Z <sup>(2)</sup>	?

(1) H = High Level; L = Low Level; Z = High Impedance or Float; X = Irrelevant; ? = Indeterminate

(2) Invalid input condition as an I<sup>2</sup>C system requires that a pullup resistor to VCC is connected.

## 9 Application and Implementation

### NOTE

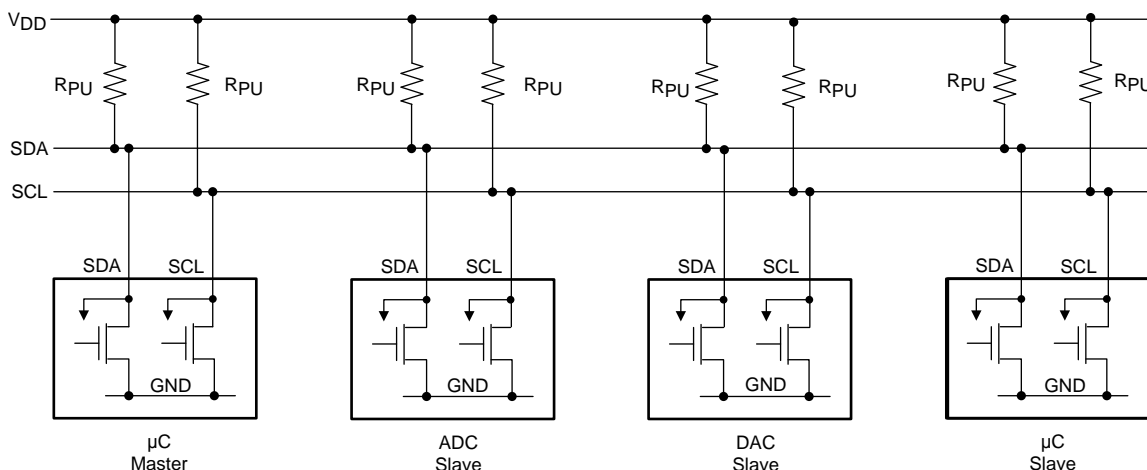
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

#### 9.1.1 I<sup>2</sup>C Bus Overview

The inter-integrated circuit (I<sup>2</sup>C) bus is a single-ended, multi-master, 2-wire bus for efficient inter-IC communication in half-duplex mode.

I<sup>2</sup>C uses open-drain technology, requiring two lines, serial data (SDA) and serial clock (SCL), to be connected to VDD by resistors (see [Figure 27](#)). Pulling the line to ground is considered a logic zero while letting the line float is a logic one. This logic is used as a channel access method. Transitions of logic states must occur while the SCL pin is low. Transitions while the SCL pin is high indicate START and STOP conditions. Typical supply voltages are 3.3 V and 5 V, although systems with higher or lower voltages are allowed.



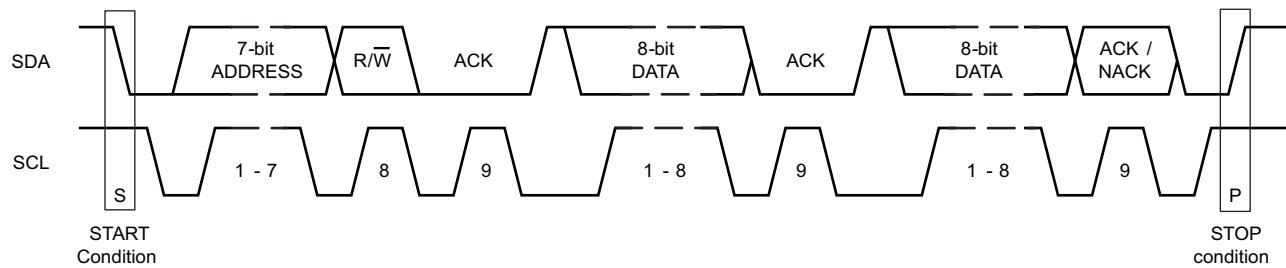
**Figure 27. I<sup>2</sup>C Bus**

I<sup>2</sup>C communication uses a 7-bit address space with 16 reserved addresses, so a theoretical maximum of 112 nodes can communicate on the same bus. In praxis, however, the number of nodes is limited by the specified, total bus capacitance of 400 pF, which restricts communication distances to a few meters.

The specified signaling rates for the ISO1540-Q1 and ISO1541-Q1 devices are 100 kbps (standard mode), 400 kbps (fast mode), 1 Mbps (fast mode plus).

The bus has two roles for nodes: master and slave. A master node issues the clock and slave addresses, and also initiates and ends data transactions. A slave node receives the clock and addresses and responds to requests from the master. [Figure 28](#) shows a typical data transfer between master and slave.

## Application Information (continued)



**Figure 28. Timing Diagram of a Complete Data Transfer**

The master initiates a transaction by creating a START condition, following by the 7-bit address of the slave it wishes to communicate with. This is followed by a single read and write (R/W) bit, representing whether the master wishes to write to 0, or to read from 1 the slave. The master then releases the SDA line to allow the slave to acknowledge the receipt of data.

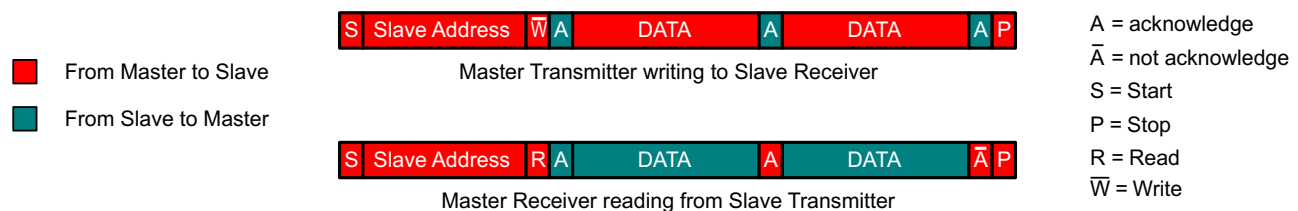
The slave responds with an acknowledge bit (ACK) by pulling the SDA pin low during the entire high time of the 9th clock pulse on the SCL signal, after which the master continues in either transmit or receive mode (according to the R/W bit sent), while the slave continues in the complementary mode (receive or transmit, respectively).

The address and the 8-bit data bytes are sent most significant bit (MSB) first. The START bit is indicated by a high-to-low transition of SDA while SCL is high. The STOP condition is created by a low-to-high transition of SDA while SCL is high.

If the master writes to a slave, it repeatedly sends a byte with the slave sending an ACK bit. In this case, the master is in master-transmit mode and the slave is in slave-receive mode.

If the master reads from a slave, it repeatedly receives a byte from the slave, while acknowledging (ACK) the receipt of every byte but the last one (see Figure 29). In this situation, the master is in master-receive mode and the slave is in slave-transmit mode.

The master ends the transmission with a STOP bit, or may send another START bit to maintain bus control for further transfers.



**Figure 29. Transmit or Receive Mode Changes During a Data Transfer**

When writing to a slave, a master mainly operates in transmit-mode and only changes to receive-mode when receiving acknowledgment from the slave.

When reading from a slave, the master starts in transmit-mode and then changes to receive-mode after sending a READ request (R/W bit = 1) to the slave. The slave continues in the complementary mode until the end of a transaction.

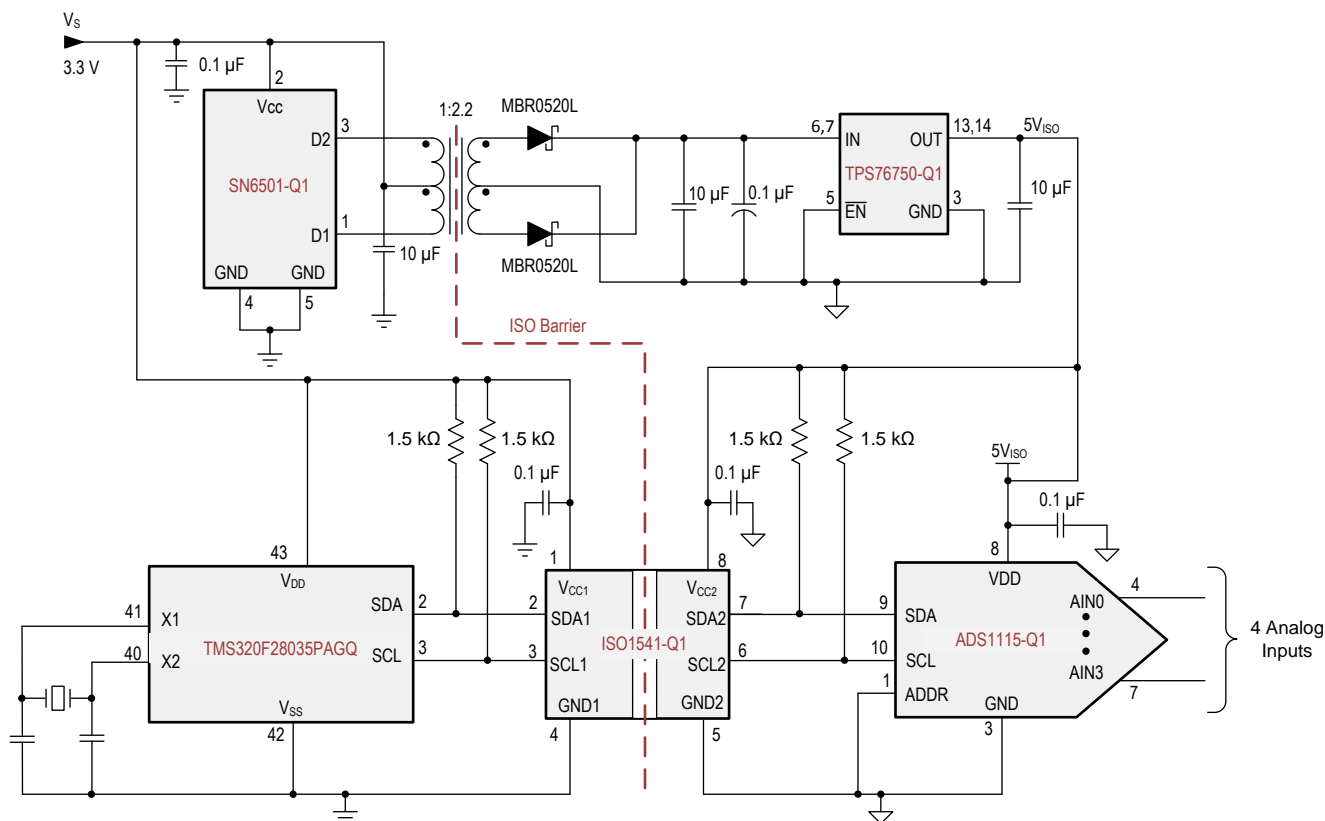
### NOTE

The master ends a reading sequence by not acknowledging (NACK) the last byte received. This procedure resets the slave state machine and allows the master to send the STOP command.

## 9.2 Typical Application

Figure 30 shows isolated I<sup>2</sup>C data acquisition system built with TI microcontroller, analog-to-digital converter, and I<sup>2</sup>C isolator, ISO1541-Q1.

The entire circuit operates from a single 3.3-V supply. A low-power push-pull converter, SN6501-Q1, drives a center-tapped transformer with an output that is rectified and linearly regulated to provide a stable 5-V supply for the data converter.



Copyright © 2016, Texas Instruments Incorporated

**Figure 30. Isolated I<sup>2</sup>C Data Acquisition System**

### 9.2.1 Design Requirements

The recommended power supply voltages (VCC1 and VCC2) must be from 3 V to 5.5 V. A recommended decoupling capacitor with a value of 0.1 µF is required between both the VCC1 and GND1 pins, and the VCC2 and GND2 pins to support of power supply voltages transient and to ensure reliable operation at all data rates.

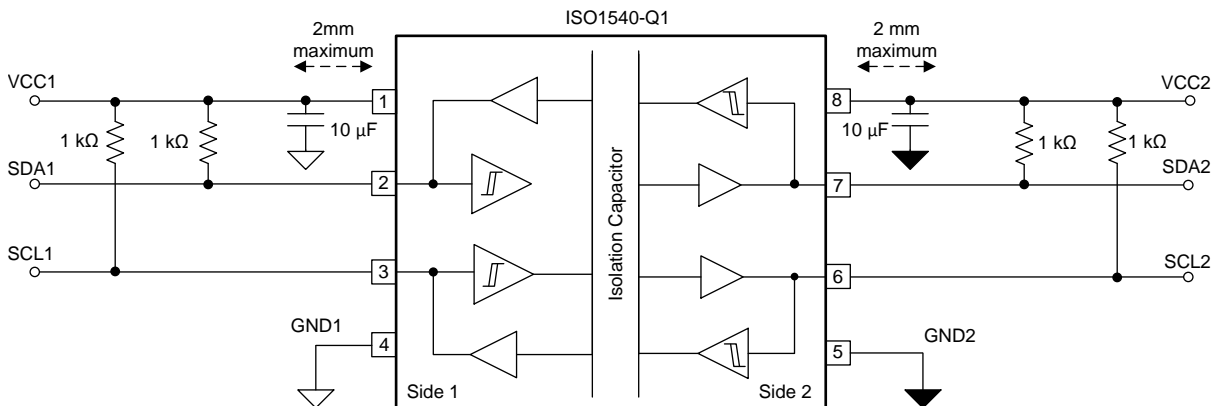
### 9.2.2 Detailed Design Procedure

The power-supply capacitor with a value of 0.1-µF must be placed as close to the power supply pins as possible. The recommended placement of the capacitors must be 2-mm maximum from input and output power supply pins (VCC1 and VCC2).

The maximum load permissible on the input lines, SDA1 and SCL1, is ≤ 40 pF and on the output lines, SDA2 and SCL2, is ≤ 400 pF.

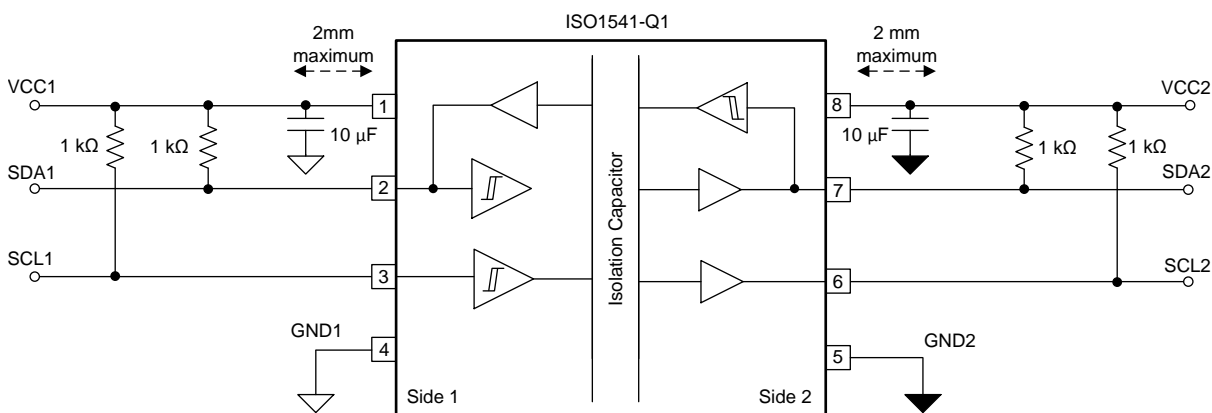
The minimum pullup resistors on the input lines, SDA1 and SCL1 to VCC1 must be selected in such a way that input current drawn is ≤ 3.5 mA. The minimum pullup resistors on the input lines, SDA2 and SCL2, to VCC2 must be selected in such a way that output current drawn is ≤ 35 mA. The maximum pullup resistors on the input lines (SDA1 and SCL1) to VCC1 and on output lines (SDA1 and SCL1) to VCC2, depends on the load and rise time requirements on the respective lines.

## Typical Application (continued)



Copyright © 2016, Texas Instruments Incorporated

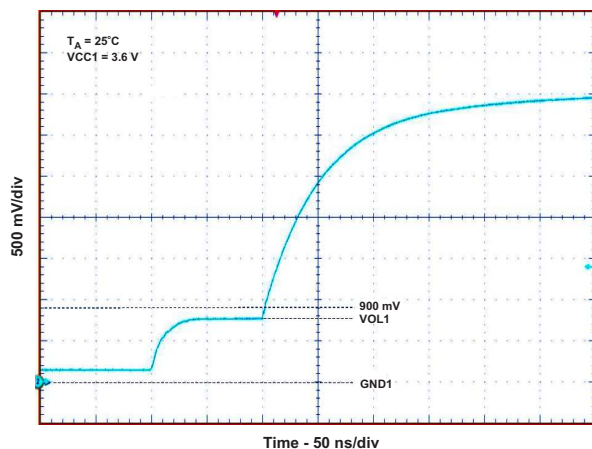
**Figure 31. Typical ISO1540-Q1 Circuit Hookup**



Copyright © 2016, Texas Instruments Incorporated

**Figure 32. Typical ISO1541-Q1 Circuit Hookup**

## 9.2.3 Application Curve



**Figure 33. Side 1: Low-to-High Transition**

## 10 Power Supply Recommendations

To help ensure reliable operation at data rates and supply voltages, TI recommends connecting a 0.1- $\mu$ F bypass capacitor at the input and output supply pins (VCC1 and VCC2). The capacitors should be placed as close to the supply pins as possible. If only a single, primary-side power supply is available in an application, isolated power can be generated for the secondary-side with the help of a transformer driver such as TI's [SN6501-Q1](#) device. For such applications, detailed power supply design and transformer selection recommendations are available in [SN6501-Q1 Transformer Driver for Isolated Power Supplies](#) (SLLSEF3).

## 11 Layout

### 11.1 Layout Guidelines

A minimum of four layers is required to accomplish a low EMI PCB design (see [Figure 34](#)). Layer stacking should be in the following order (top-to-bottom): high-speed signal layer, ground plane, power plane and low-frequency signal layer.

- Routing the high-speed traces on the top layer avoids the use of vias (and the introduction of their inductances) and allows for clean interconnects between the isolator and the transmitter and receiver circuits of the data link.
- Placing a solid ground plane next to the high-speed signal layer establishes controlled impedance for transmission line interconnects and provides an excellent low-inductance path for the return current flow.
- Placing the power plane next to the ground plane creates additional high-frequency bypass capacitance of approximately 100 pF/in<sup>2</sup>.
- Routing the slower speed control signals on the bottom layer allows for greater flexibility as these signal links usually have margin to tolerate discontinuities such as vias.

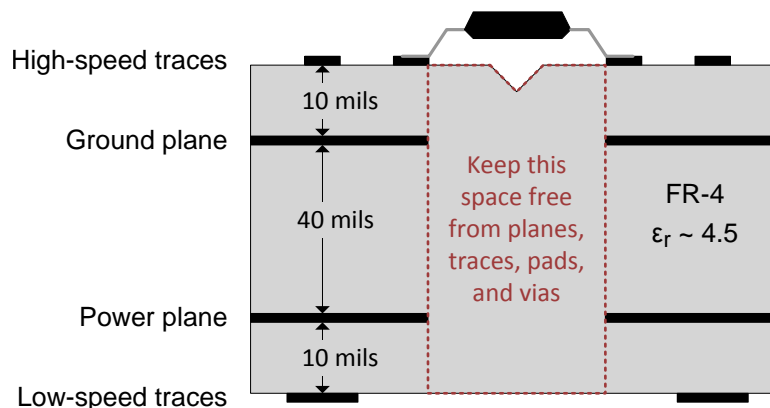
If an additional supply voltage plane or signal layer is needed, add a second power or ground plane system to the stack to keep it symmetrical. This makes the stack mechanically stable and prevents it from warping. Also the power and ground plane of each power system can be placed closer together, thus increasing the high-frequency bypass capacitance significantly.

For detailed layout recommendations, see the [Digital Isolator Design Guide](#) (SLLA284)

#### 11.1.1 PCB Material

For digital circuit boards operating at less than 150 Mbps, (or rise and fall times greater than 1 ns), and trace lengths of up to 10 inches, use standard FR-4 UL94V-0 printed circuit board. This PCB is preferred over cheaper alternatives because of lower dielectric losses at high frequencies, less moisture absorption, greater strength and stiffness, and the self-extinguishing flammability-characteristics.

### 11.2 Layout Example



**Figure 34. Recommended Layer Stack**



## 12 Device and Documentation Support

### 12.1 Documentation Support

#### 12.1.1 Related Documentation

For related documentation see the following:

- [Digital Isolator Design Guide](#) (SLLA284)
- [TI Isolation Glossary](#) (SLLA353)
- [SN6501-Q1 Transformer Driver for Isolated Power Supplies](#). (SLLSEF3)
- [TPS767xx-Q1 Fast-Transient-Response 1-A Low-Dropout Voltage Regulators](#) (SGLS009)
- [ADS1115-Q1 Low-Power, 16-Bit Analog-to-Digital Converter With Internal Reference](#) (SBAS563)
- [TMS320F2803x Piccolo™ Microcontrollers](#) (TMS320F2803x Piccolo™ Microcontrollers)

### 12.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 3. Related Links**

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
ISO1540-Q1	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>
ISO1541-Q1	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 12.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 12.4 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 12.5 Trademarks

Piccolo, E2E are trademarks of Texas Instruments.  
All other trademarks are the property of their respective owners.

### 12.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 12.7 Glossary

**SLYZ022** — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
ISO1540QDQ1	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I1540Q	<a href="#">Samples</a>
ISO1540QDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I1540Q	<a href="#">Samples</a>
ISO1541QDQ1	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I1541Q	<a href="#">Samples</a>
ISO1541QDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	I1541Q	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

---

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF ISO1540-Q1, ISO1541-Q1 :**

- Catalog: [ISO1540](#), [ISO1541](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ISO1540QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
ISO1541QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS

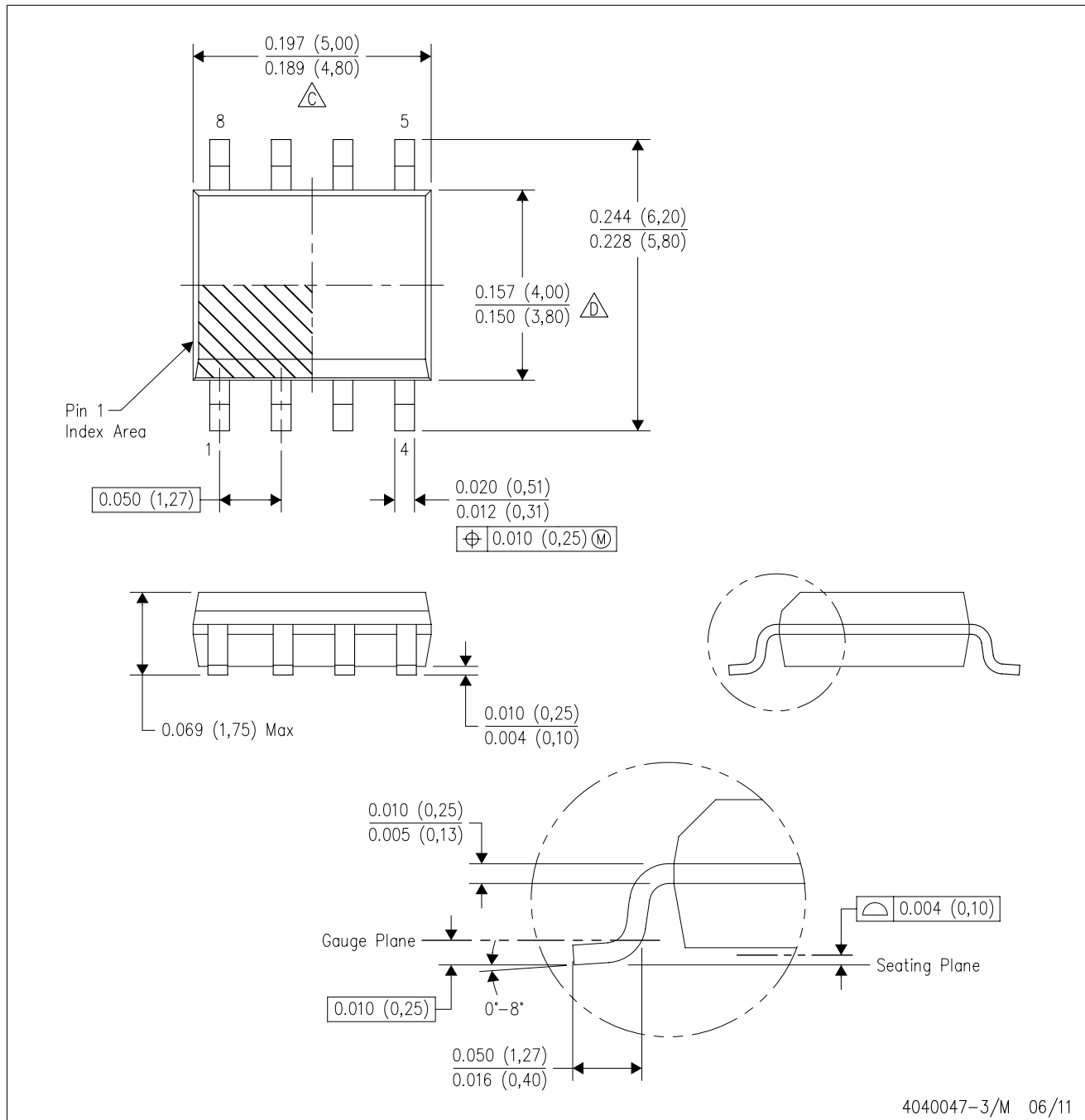


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ISO1540QDRQ1	SOIC	D	8	2500	367.0	367.0	38.0
ISO1541QDRQ1	SOIC	D	8	2500	367.0	367.0	38.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



4211283-2/E 08/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)